



# STPS60H100C

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

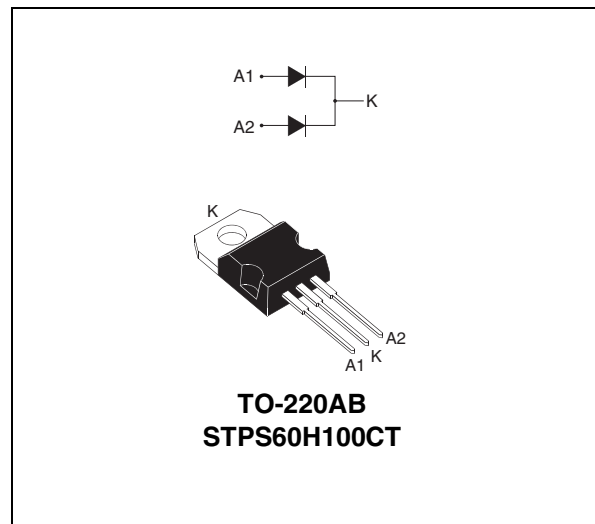
$I_{F(AV)}$	2 x 30 A
$V_{RRM}$	100 V
$T_j$	175°C
$V_F(max)$	0.72 V

### FEATURES AND BENEFITS

- High junction temperature capability
- Low leakage current
- Low thermal resistance
- High frequency operation
- Avalanche specification

### DESCRIPTION

Dual center tab Schottky rectifier suited for High Frequency server and telecom base station SMPS. Packaged in TO-220AB, this device combines high current rating and low volume to enhance both reliability and power density of the application.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	100	V
$I_{F(RMS)}$	RMS forward current	60	A
$I_{F(AV)}$	Average forward current $T_c = 150^\circ\text{C}$ $\delta = 0.5$	Per diode 30 Per device 60	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ms}$ sinusoidal	300 A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1\mu\text{s}$ $T_j = 25^\circ\text{C}$	18100 W
$T_{stg}$	Storage temperature range	-65 to + 175	°C
$T_j$	Maximum operating junction temperature *	175	°C
dV/dt	Critical rate of rise of reverse voltage	10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} > \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink

### Order Codes

Part Number	Marking
STPS60H100CT	STPS60H100CT

## STPS60H100C

### THERMAL RESISTANCE

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	1.0	$^{\circ}\text{C}/\text{W}$
		Total	0.7	
$R_{th(c)}$		Coupling	0.4	

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

### STATIC ELECTRICAL CHARACTERISTICS (per diode)

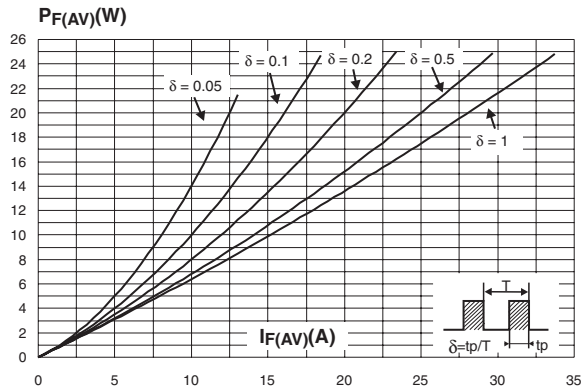
Symbol	Parameter	Tests conditions		Min.	Typ	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$		2	10	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$			3	10	mA
$V_F^{**}$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 30\text{A}$			0.84	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 30\text{A}$		0.67	0.72	
		$T_j = 25^{\circ}\text{C}$	$I_F = 60\text{A}$		0.92	0.98	
		$T_j = 125^{\circ}\text{C}$	$I_F = 60\text{A}$		0.8	0.84	

Pulse test: \*  $t_p = 5 \text{ ms}$ ,  $\delta < 2\%$

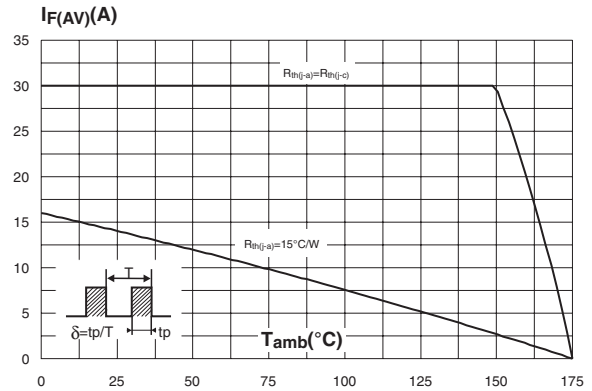
\*\*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:  $P = 0.6 \times I_{F(AV)} + 0.004 I_{F(RMS)}^2$

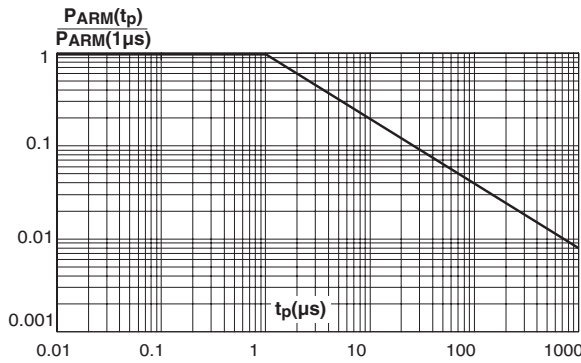
**Fig 1:** Average forward power dissipation versus average forward current (per diode).



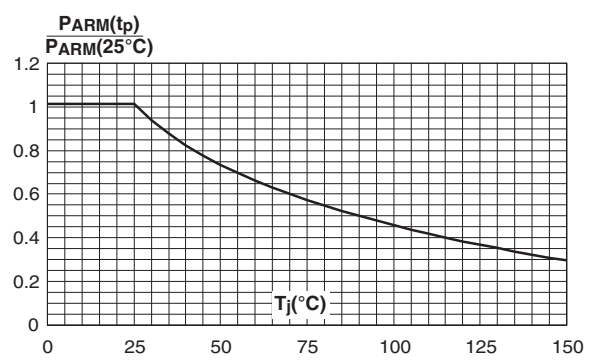
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode).



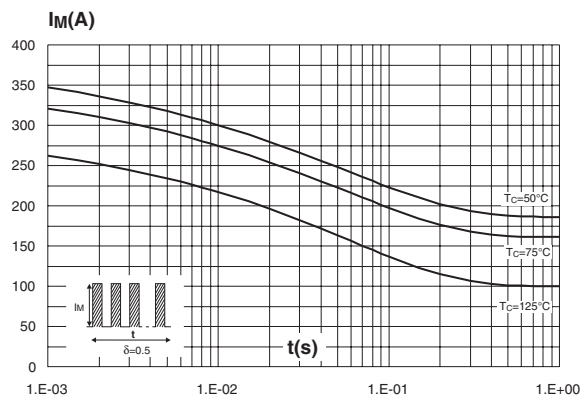
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



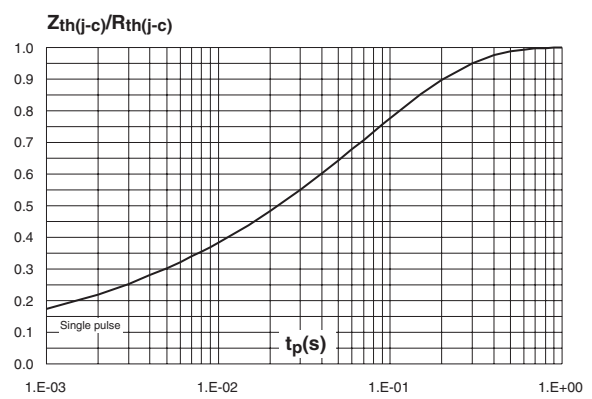
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



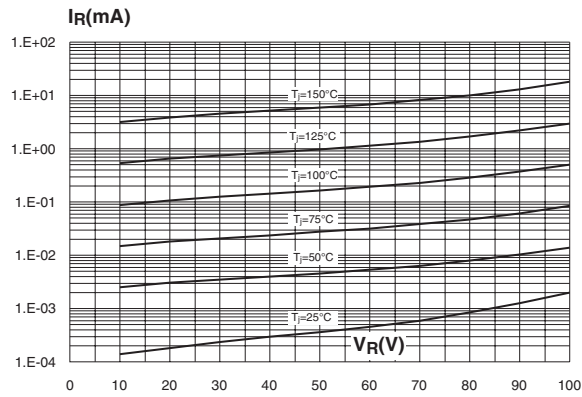
**Fig. 5:** Non repetitive surge peak forward current versus overload duration.



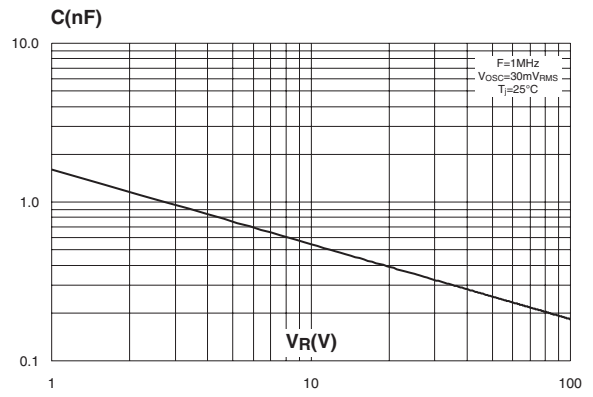
**Fig. 6:** Relative variation of thermal impedance junction to case versus pulse.



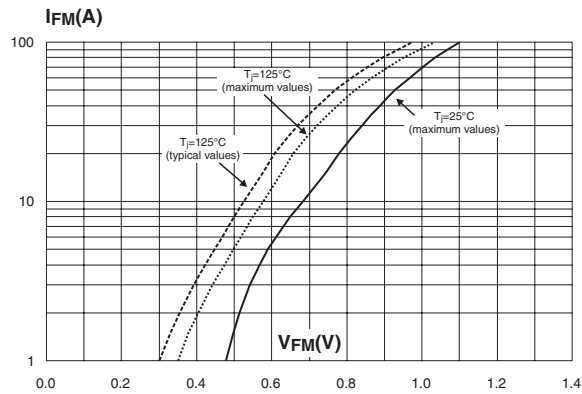
**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values).

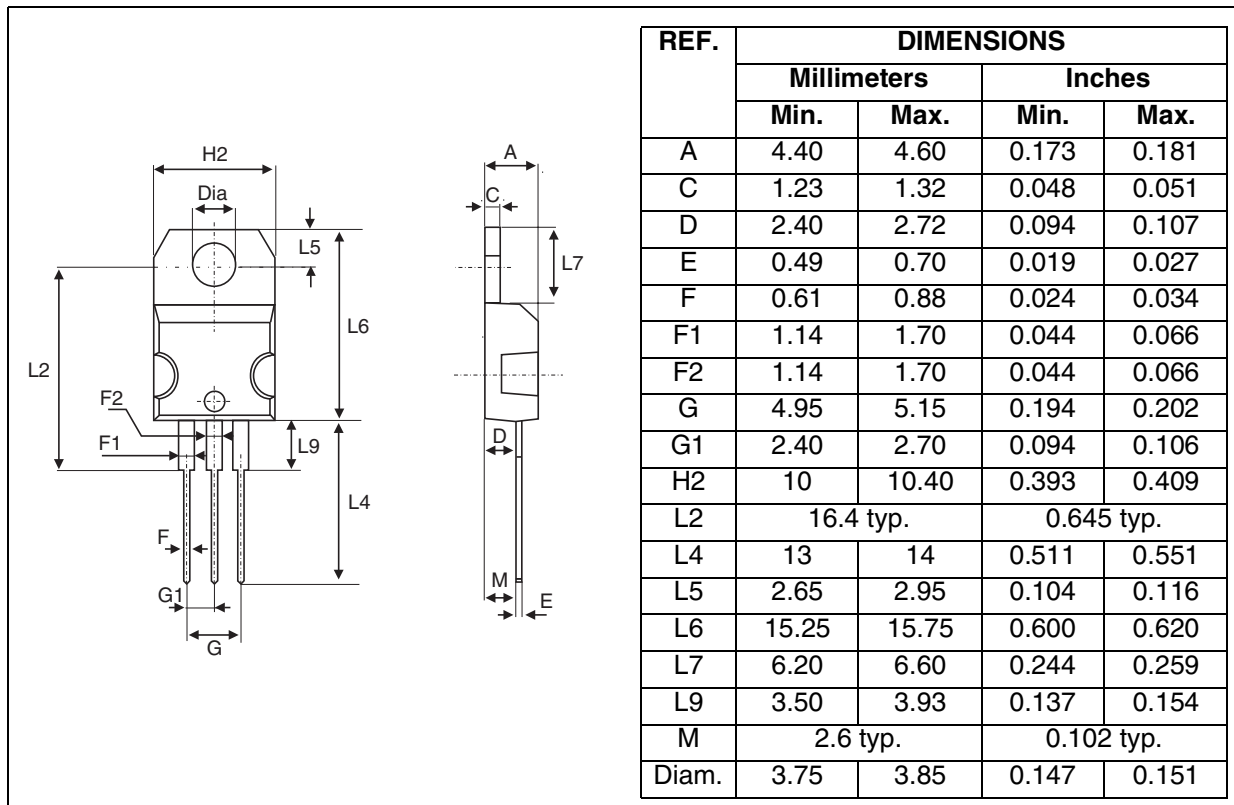


**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values).



**Fig. 9:** Forward voltage drop versus forward current.



**PACKAGE MECHANICAL DATA**  
 TO-220AB

**ORDERING INFORMATION**

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS60H100CT	STPS60H100CT	TO-220AB	2.20 g	50	Tube

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 m.N.
- Maximum torque value: 1.0 m.N.

**REVISION HISTORY**
**Table 1:** Revision history

Date	Revision	Description of Changes
02-Aug-2004	1	First issue

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